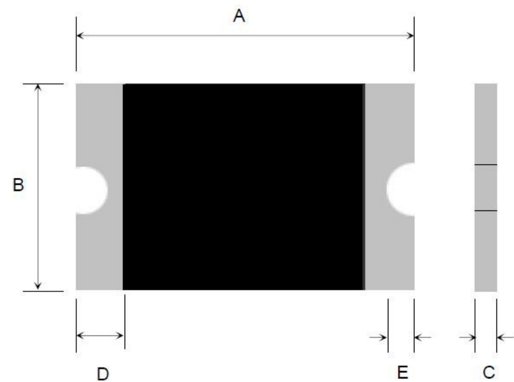
TERMINAL PAD SOLDERABILITY:
Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.



TERMINAL PAD MATERIALS:

Tin-Plated Nickel-Copper
Lead-Free，ROHS Compliant

TABLE I. DIMENSIONS:

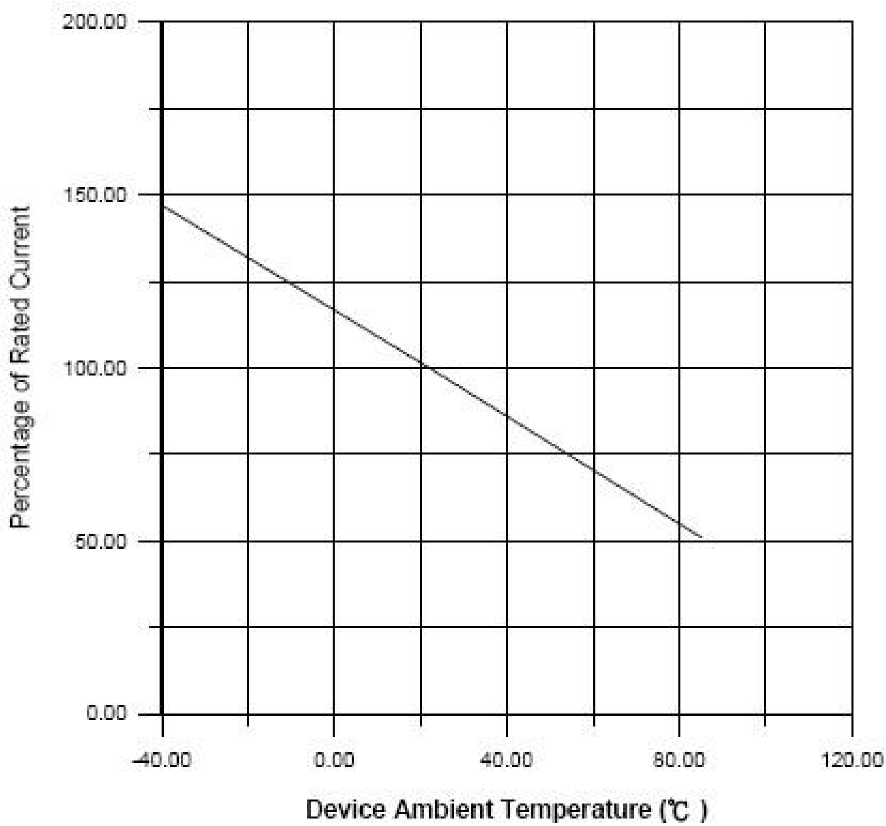
Unit：mm

Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
1812-075/13.2V	4.37	4.73	3.07	3.41	0.40	0.90	0.30	0.25

TABLE II. PERFORMANCE RATINGS:

Model	Vmax	Imax	Ihold@25℃	Itrip@25℃	Pd Typ.	Maximum Time TO Trip		Resistance	
	(Vdc)	(A)	(A)	(A)	(W)	Current (A)	Time (Sec)	Rimin (Ω)	Rimax (Ω)
1812-075/13.2V	13.2	100	0.75	1.50	0.8	8.0	0.20	0.090	0.450

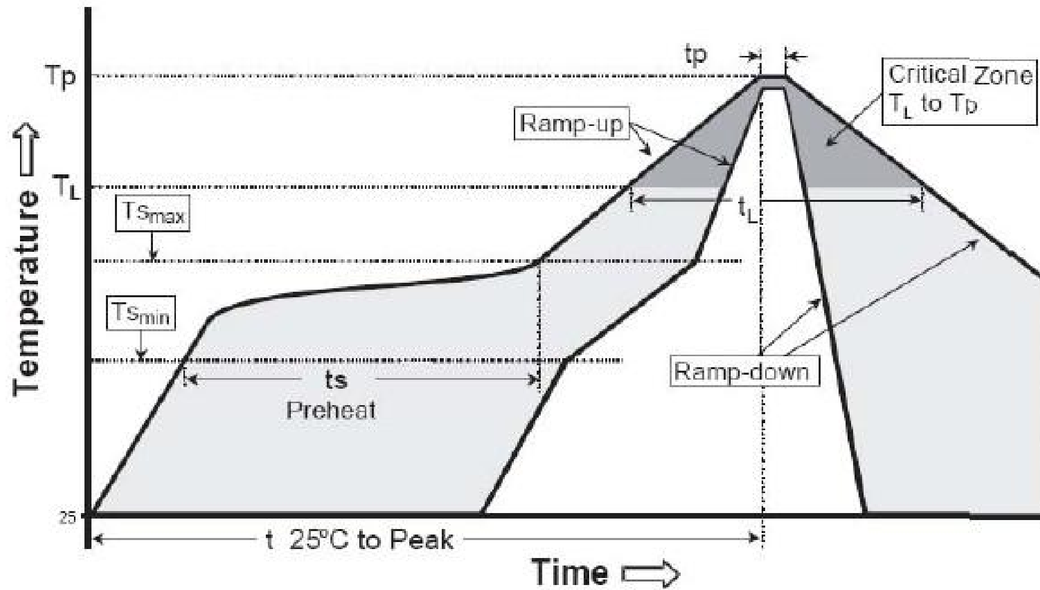
THERMAL DERATING CURVE FOR SMD1812 SERIES



THERMAL DERATING CHART FOR SMD1812 SERIES-IHOLD(Amps) RECOMMENDED DATA

Model	Ambient Operation Temperature								
	-40℃	-20℃	0℃	23℃	40℃	50℃	60℃	70℃	85℃
1812-075/13.2V	1.10	0.99	0.87	0.75	0.63	0.57	0.49	0.45	0.35

SOLDER REFLOW



RECOMMENDED CONCITIONS

Profile Feature	Pd-Free Assembly
Average Ramp-Up Rate(Tsmax to Tp)	3℃/second max
Preheat —Temperature Min(Tsmin) —Temperature Max(Tsmax) —Time(Tsmin to Tsmax)	150℃ 200℃ 60-180seconds
Time maintained above： —Temperature(TL) —Time(tL)	217℃ 60-150seconds
Peak Temperature(Tp)	260℃
Time within 5℃ of actual Peak Temperature(tp)	20-40seconds
Ramp-Down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8minutes max.
Storage Condition	0℃~35℃，≤70%RH

Note： 1.All temperature refer to topside of the package，measured on the package body surface.
2.If reflow temperature exceed the recommended profile，devices

PACKAGING

Part Number	Component Package	Quantity
1812-075/13.2V	1812	1500